

# FAST CMOS 18-BIT R/W BUFFER

## IDT54/74FCT162701T/AT

## **FEATURES:**

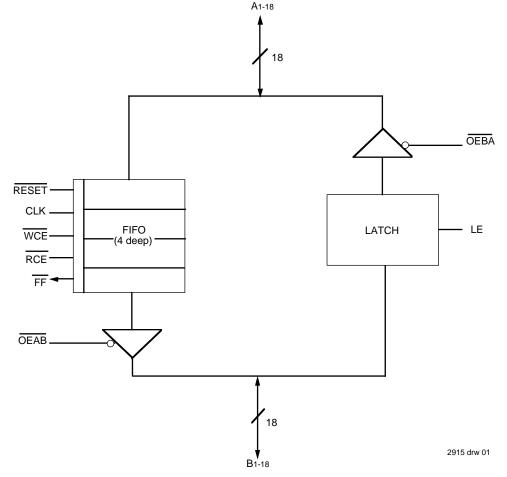
- 0.5 MICRON CMOS Technology
- Typical tsk(o) (Output Skew) < 250ps
- Low input and output leakage ≤1μA (max.)
- ESD > 2000V per MIL-STD-883, Method 3015;
   > 200V using machine model (C = 200pF, R = 0)
- Packages include 25 mil pitch SSOP, 19.6 mil pitch TSSOP, 15.7 mil pitch TVSOP and 25 mil pitch Cerpack
- Extended commercial range of -40°C to +85°C
- Balanced Output Drivers: ±24mA (commercial), ±16mA (military)
- · Reduced system switching noise
- Typical Volp (Output Ground Bounce) < 0.6V at VCC = 5V, TA = 25°C
- Ideal for new generation x86 write-back cache solutions
- · Suitable for modular x86 architectures
- Four deep write FIFO
- Latch in read path
- · Synchronous FIFO reset

#### **DESCRIPTION:**

The FCT162701T/AT is an 18-bit Read/Write buffer with a four deep FIFO and a read-back latch. It can be used as a read/write buffer between a CPU and memory or to interface a high-speed bus and a slow peripheral. The A-to-B (write) path has a four deep FIFO for pipelined operations. The FIFO can be reset and a FIFO full condition is indicated by the full flag ( $\overline{\text{FF}}$ ). The B-to-A (read) path has a latch. A HIGH on LE, allows data to flow transparently from B-to-A. A LOW on LE allows the data to be latched on the falling edge of LE.

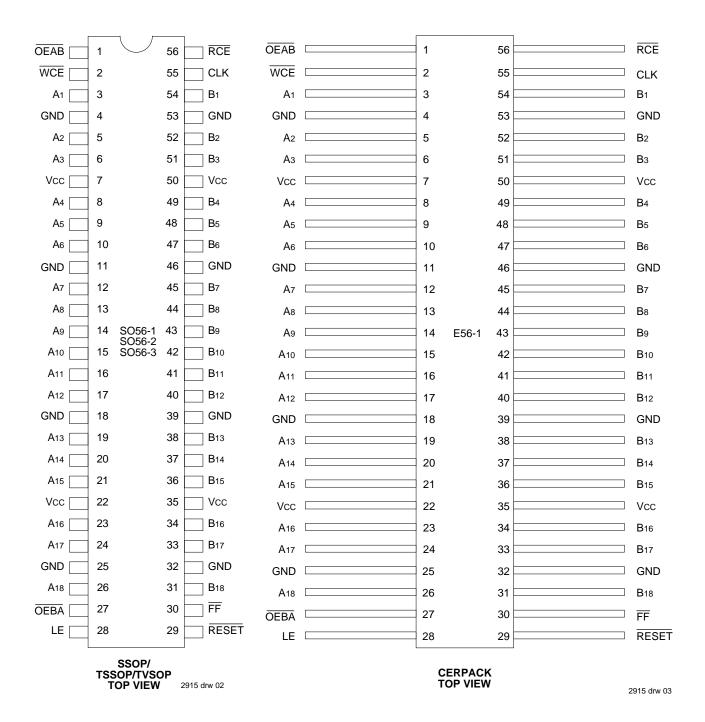
The FCT162701T/AT has a balanced output drive with series termination. This provides low ground bounce, minimal undershoot and controlled output edge rates.

## **FUNCTIONAL BLOCK DIAGRAM**



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# **PIN CONFIGURATIONS**



# PIN DESCRIPTION

Pin Names	I/O	Description
A1-18	I/O	18 bit I/O port.
B1-18	I/O	18 bit I/O port.
CLK	_	Clock for write path FIFO. Clocks data into FIFO when $\overline{WCE}$ is low, clocks data out of FIFO when $\overline{RCE}$ is low. When FIFO is full all further writes to the FIFO are inhibited. When FIFO is empty all reads from the FIFO are inhibited. CLK also resets the FIFO when $\overline{RESET}$ is low.
WCE	I	Enable pin for FIFO input clock.
RCE	I	Enable pin for FIFO output clock.
FF	0	Write path FIFO full flag. Goes low when FIFO is full.
RESET	_	Synchronous FIFO reset - when low CLK resets the FIFO. The FIFO pointers are initialized to the "empty" condition and FIFO output is forced high (all ones). The FIFO full flag (FF) will be high immediately after reset.
OEAB	I	Output Enable pin for B port.
OEBA	Ī	Output Enable pin for A port.
LE	I	Read path latch enable pin. When high, data flows transparently from B port to A port, B data is latched on the falling edge of LE.

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# ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Description	Max.	Unit
VTERM <sup>(2)</sup>	GND	0.0 10 11.0	V
VTERM(3)	Terminal Voltage with Respect to	–0.5 to	V
	GND	Vcc +0.5	
Tstg	Storage Temperature	-65 to +150	°C
Іоит	DC Output Current	-60 to +120	mA

NOTES:

- 1. Stresses greater than those listed under ABSOLUTE MAXIMUM RAT-INGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- 2. All device terminals except FCT162XXXT Output and I/O terminals.
- 3. Output and I/O terminals for FCT162XXXT.

# **CAPACITANCE** (TA = +25°C, f = 1.0MHz)

Symbol	Parameter <sup>(1)</sup>	Conditions	Тур.	Max.	Unit
CIN	Input	VIN = 0V	3.5	6.0	pF
	Capacitance				
CI/O	I/O	Vout = 0V	3.5	8.0	pF
	Capacitance				
NOTE- 2915 Ink 03					

1. This parameter is measured at characterization but not tested.

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#### **FUNCTIONAL DESCRIPTION:**

This device is useful as a read/write buffer for modular high end designs. It provides multi-level buffering in the write path and single deep buffering in the read path, and is suited to write back cache implementation. The read path provides a transparent latch.

The four deep FIFO uses one clock with two clock enable pins, WCE and RCE to clock data in and out. The FIFO has an external full flag which goes LOW when the FIFO is full. Internal read and write pointers keep track of the words stored in the FIFO. A write attempt to a full FIFO is ignored. An attempt to read from an empty FIFO will have no effect and the last read data remains at the output of the FIFO. The FIFO may be reset by the synchronous RESET input. This resets

the read and write pointers to the original "empty" condition and also sets all B outputs = 1. Simultaneous read and write attempts (clock data into FIFO as well as clock data out of FIFO) are possible except on FIFO empty and full boundaries. When the FIFO is empty, and a simultaneous read and write is attempted, the read is ignored while the write is executed. If the same is attempted when the FIFO is full, the write is ignored while the read is executed. Normal operation of the four deep FIFO in the write path is independent of the read path operation.

Power, ground and data pin positions on the FCT162701T match those on the FCT16501T/162501T, allowing an easy upgrade.

### **APPLICATIONS: 486 INTERFACE**

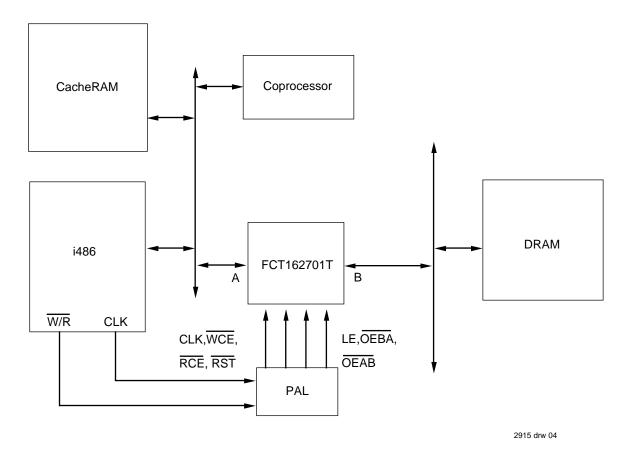


Figure 1. FCT162701T Application Example

# DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Commercial: TA = -40°C to +85°C, VCC =  $5.0V \pm 10\%$ ; Military: TA = -55°C to +125°C, VCC =  $5.0V \pm 10\%$ 

Symbol	Parameter	Test Cor	nditions <sup>(1)</sup>	Min.	Typ. <sup>(2)</sup>	Max.	Unit
ViH	Input HIGH Level	Guaranteed Logic HIGH Level		2.0	_	1	V
VIL	Input LOW Level	Guaranteed Logic LOW	Level	_	_	0.8	V
Іін	Input HIGH Current (Input pins)(5)	Vcc = Max.	VI = VCC	_	_	±1	μΑ
	Input HIGH Current (I/O pins) <sup>(5)</sup>			_	_	±1	
lıL	Input LOW Current (Input pins) <sup>(5)</sup>		Vı = GND	_	_	±1	
	Input LOW Current (I/O pins) <sup>(5)</sup>			_	_	±1	
lozh	High Impedance Output Current	Vcc = Max.	Vo = 2.7V	_	_	±1	μΑ
lozL	(3-State Output pins) <sup>(5)</sup>		Vo = 0.5V	_	_	±1	
Vık	Clamp Diode Voltage	Vcc = Min., IIN = -18mA		_	-0.7	-1.2	V
los	Short Circuit Current	Vcc = Max., Vo = GND <sup>(3)</sup>		-80	-140	-225	mA
Vн	Input Hysteresis	_		_	100	_	mV
ICCL ICCH ICCZ	Quiescent Power Supply Current	Vcc = Max., Vin = GND	or Vcc	_	5	500	μА

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# **OUTPUT DRIVE CHARACTERISTICS**

Symbol	Parameter	Test Conditions <sup>(1)</sup>			Typ. <sup>(2)</sup>	Max.	Unit
IODL	Output LOW Current	$VCC = 5V$ , $VIN = VIH or VIL$ , $VOUT = 1.5V^{(3)}$		60	115	200	mA
lodh	Output HIGH Current	$VCC = 5V$ , $VIN = VIH or VIL$ , $VOUT = 1.5V^{(3)}$		-60	-115	-200	mA
Voн	Output HIGH Voltage	VCC = Min. VIN = VIH or VIL	Iон = −16mA MIL. Iон = −24mA COM'L.	2.4	3.3	_	V
Vol	Output LOW Voltage	VCC = Min. VIN = VIH or VIL	IOL = 16mA MIL. IOL = 24mA COM'L.	_	0.3	0.55	V

#### NOTES:

- 2915 lnk 05
- 1. For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.
- 2. Typical values are at Vcc = 5.0V, +25°C ambient.
- 3. Not more than one output should be tested at one time. Duration of the test should not exceed one second.
- 4. Duration of the condition can not exceed one second.
- 5. The test limit for this parameter is  $\pm$  5 $\mu$ A at TA = -55°C.

# **POWER SUPLY CHARACTERISTICS**

Symbol	Parameter	Test Conditions <sup>(1)</sup>			Min.	Typ. <sup>(2)</sup>	Max.	Unit
ΔΙCC	Quiescent Power Supply Current TTL Inputs HIGH	VCC = Max. $VIN = 3.4V^{(3)}$			_	0.5	1.5	mA
ICCD (CLK)	Dynamic Power Supply Current due to clock switching <sup>(4)</sup>	Vcc = Max. Outputs Open	CLK Toggling 50% Duty Cycle	VIN = VCC VIN = GND	_	180	240	μΑ/ MHz
ICCD (O/P)	Dynamic Power Supply Current due to output switching <sup>(4)</sup>		One Bit Toggling 50% Duty Cycle		_	80	120	
Ic	Total Power Supply Current <sup>(6)</sup>	Vcc = Max. Outputs Open fcP= 10MHz 50% Duty Cycle		VIN = VCC VIN = GND	_	1.8	2.9 <sup>(5)</sup>	mA
		OEAB = GND; OEBA = Vcc LE = WCE = RCE = GND RESET = Vcc All Inputs Low		VIN = 3.4V VIN = GND	_	2.1	3.7 <sup>(5)</sup>	
		Vcc = Max. Outputs Open fcP= 10MHz 50% Duty Cycle		VIN = VCC VIN = GND	_	2.2	3.5	
		OEAB = GND; LE = WCE = RO RESET = Vcc One Bit Togglir at fo = 5MHz 50% Duty Cycl	OEBA = Vcc CE = GND	VIN = 3.4V VIN = GND	_	2.7	5.0	

NOTES: 2915 tbl 06

- For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.
   Typical values are at Vcc = 5.0V, +25°C ambient.
- 3. Per TTL driven input (VIN) = 3.4V). All other inputs at Vcc or GND.
- 4. This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.
- 5. Values for these conditions are examples of the lcc formula. These limits are guaranteed but not tested.
- 6. IC = IQUIESCENT + INPUTS + IDYNAMIC
  - $IC = ICC + \Delta ICC DHNT + ICCD (CLK) X fCP + ICCD (O/P) X fO NO$
  - Icc = Quiescent Current (IccL, IccH and Iccz)
  - $\Delta$ Icc = Power Supply Current for a TTL High Input (VIN = 3.4V)
  - DH = Duty Cycle for TTL Inputs High
  - NT = Number of TTL Inputs at D
  - ICCD = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)
  - fcP = Clock Frequency for Register Devices (Zero for Non-Register Devices)
  - fo = Output Frequency
  - No = Number of Outputs at fo

# SWITCHING CHARACTERISTICS OVER OPERATING RANGE

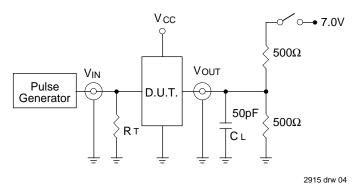
			FCT1	FCT162701T		FCT162701AT		
	Parameter	Test Conditions <sup>(1)</sup>	Min. <sup>(2)</sup>	Max. <sup>(2)</sup>	Min. <sup>(2)</sup>	Max. <sup>(2)</sup>	Unit	
PROPAG	ATION DELAYS	-	•	•	-			
1	B1-18 to A 1-18	Read path/latch	1.5	6.5	1.5	5.5	ns	
2	LE (Low to Hi) to A 1-18	Read path/latch	1.5	5.7	1.5	4.7	ns	
3	CLK to FF	Write path	2	7.0	2	6.0	ns	
4	CLK to B1-18	Write path	1	6.0	1	5.2	ns	
SETUP &	HOLD TIMES(3)		•	-	•			
5	A1-18 to CLK (Low to Hi) Setup	Write path	2.5	_	2.5	_	ns	
6	A1-18 to CLK (Low to Hi) Hold	Write path	0	_	0		ns	
7	B1-18 to LE (Hi to Low) Setup	Read path/latch	3	_	3		ns	
8	B1-18 to LE (Hi to Low) Hold	Read path/latch	0	_	0		ns	
9	WCE, RCE (Low) to CLK Setup	Write path	3	_	3	_	ns	
10	WCE, RCE (Low) to CLK Hold	Write path	0	_	0	_	ns	
11	RESET (Low) to CLK Setup	Write path	3	_	3	_	ns	
12	RESET (Low) to CLK Hold	Write path	0	_	0	_	ns	
ENABLE	& DISABLE TIMES <sup>(3)</sup>		•	-	•			
13	OEBA Low to A1-18 Enable	Write path	1.5	7.0	1.5	6.0	ns	
14	OEBA High to A1-18 Disable	Write path	1.5	6.0	1.5	5.0	ns	
15	OEAB Low to B1-18 Enable	Read path	1.5	7.0	1.5	6.0	ns	
16	OEAB High to B1-18 Disable	Read path	1.5	6.0	1.5	5.0	ns	
MINIMUM	PULSE WIDTHS		-	-	-	-		
17	CLK HIGH or LOW Pulse Width	Write path	3.0	_	3.0	_	ns	
18	LE HIGH Pulse Width	Read path/latch	3.0	_	3.0		ns	

NOTES:

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- 1. See test circuit and waveforms.
- 2. Minimum limits are guaranteed but not tested on Propagation Delays.
- 3. Guaranteed but not tested.

# TEST CIRCUITS AND WAVEFORMS TEST CIRCUITS FOR ALL OUTPUTS



### **SWITCH POSITION**

Test	Switch
Open Drain Disable Low	Closed
Enable Low	
All Other Tests	Open

#### **DEFINITIONS:**

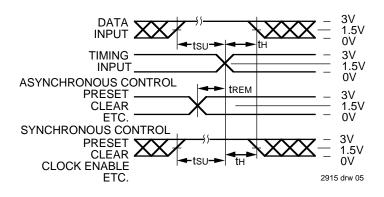
2915 lnk 07

CL= Load capacitance: includes jig and probe capacitance.

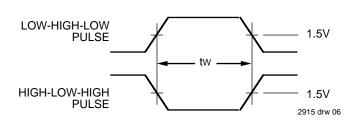
 $\mathsf{RT} = \mathsf{Termination}$  resistance: should be equal to  $\mathsf{ZOUT}$  of the Pulse Generator.

# SET-UP, HOLD AND RELEASE TIMES

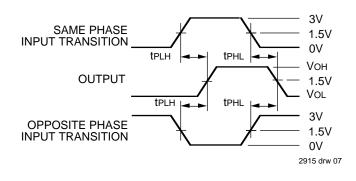
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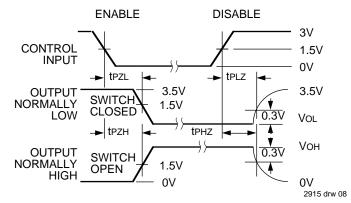
#### **PULSE WIDTH**



### PROPAGATION DELAY



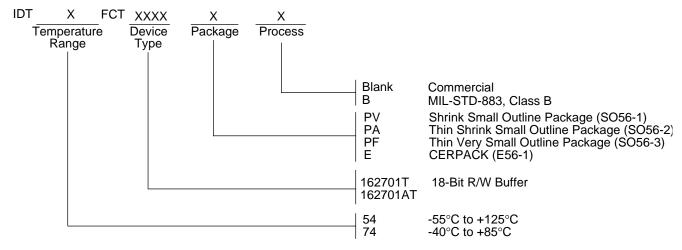
### **ENABLE AND DISABLE TIMES**



#### NOTES:

- Diagram shown for input Control Enable-LOW and input Control Disable-HIGH
- 2. Pulse Generator for All Pulses: Rate ≤ 1.0MHz; tF ≤ 2.5ns; tR ≤ 2.5ns

# ORDERING INFORMATION



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